

LUTONG WANG

Ph.D. Student, Electrical and Computer Engineering Department, University of California at San Diego

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EDUCATION **University of California, San Diego, CA** 09/2014 – Present
Ph.D. in Department of Computer Science and Engineering
GPA: 3.9/4.0
University of California, San Diego, CA 09/2014 – 06/2016
M.S. in Electrical and Computer Engineering
Tsinghua University, Beijing, China 09/2010 – 07/2014
B.S. in Microelectronics

RESEARCH *Improved Physical Design for Placement Optimization* UC San Diego
EXPERIENCE - RePlAcE: Improved Solution Quality and Validation of Routable Placements
- Optimal Multi-Row Detailed Placement for Yield and Model-Hardware
Correlation Improvements [C5]
- Vertical M1 Routing-Aware Detailed Placement for Congestion and
Wirelength Reduction [C4]
Improved Physical Design for Low Power Optimization UC San Diego
- Improved Flop Tray-Based Design Implementation for Power Reduction [C2]
DFM Methodologies for Advanced Nodes UC San Diego
- ILP-Based Co-Optimization of Cut-Mask Layout, Dummy Fill and Timing
for Sub-14nm BEOL Technology [C1]
- MILP-Based Optimization of 2D Block Masks for Timing-Aware Dummy
Segment Removal in Self-Aligned Multiple Patterning Layouts [J1]

PUBLICATIONS [J1] K. Han, A. B. Kahng, H. Lee and **L. Wang**, “MILP-Based Optimization of 2D Block Masks for
(AUTHORS ARE Timing-Aware Dummy Segment Removal in Self-Aligned Multiple Patterning Layouts”, *IEEE*
ALPHABETICALLY *Transactions on Computer-Aided Design of Integrated Circuits and Systems* 36(7) (2017), pp.
ORDERED) 1075-1088.
[C5] C. Han, K. Han, A. B. Kahng, H. Lee, **L. Wang** and B. Xu, “Optimal Multi-Row Detailed
Placement for Yield and Model-Hardware Correlation Improvements in Sub-10nm VLSI”,
IEEE/ACM International Conference on Computer-Aided Design, 2017, to appear.
[C4] K. Han, A. B. Kahng, H. Lee and **L. Wang**, “Vertical M1 Routing-Aware Detailed Placement for
Congestion and Wirelength Reduction in Sub-10nm Nodes”, *ACM/EDAC/IEEE Design
Automation Conference*, 2017, pp 51:1-51:6.
[C3] K. Han, A. B. Kahng, H. Lee and **L. Wang**, “Performance- and Energy-Aware Optimization of
BEOL Interconnect Stack Geometry in Advanced Technology Nodes”, *IEEE International
Symposium on Quality Electronic Design*, 2017, pp. 104-110. (**Invited Paper**)
[C2] A. B. Kahng, J. Li and **L. Wang**, “Improved Flop Tray-Based Design Implementation for Power
Reduction”, *IEEE/ACM International Conference on Computer-Aided Design*, 2016, pp. 20:1-
20:8. (nominated for **Best Paper award**)
[C1] K. Han, A. B. Kahng, H. Lee and **L. Wang**, “ILP-Based Co-Optimization of Cut-Mask Layout,
Dummy Fill and Timing for Sub-14nm BEOL Technology”, *SPIE Photomask Technology*, 2015,
pp. 96350E. (nominated for **Best Paper award**)

SKILLS [Languages] C/C++, Tk/Tcl, Python, Matlab, Verilog
[Tools] SoC Encounter / Innovus / ICC, Tempus / PrimeTime, Design Compiler,
Quantus / Star-RCXT, HSPICE, CPLEX
[Others] LaTeX, Word, Excel, PowerPoint
